

#21/8 2/21/03 (NE) 1802030,

## IN THE UNITED STATES PATENT & TRADEMARK OFFICE

IN RE APPLICATION OF

:

HIROYUKI YANO ET AL

: EXAMINER: DEO, D. V.

SERIAL NO: 09/531,163

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FILED: MARCH 17, 2000

: GROUP ART UNIT: 1765

FOR: AQUEOUS DISPERSION,

AQUEOUS DISPERSION FOR CHEMICAL MECHANICAL POLISHING USED FOR MANUFACTURE OF

SEMICONDUCTOR DEVICES,

METHOD FOR MANUFACTURE OF SEMICONDUCTOR DEVICES, AND METHOD FOR FORMATION OF

EMBEDDED WIRING

## AMENDMENT AND REQUEST FOR RECONSIDERATION

ASSISTANT COMMISSIONER FOR PATENTS WASHINGTON, D.C. 20231

SIR:

Responsive to the Office Action of November 15, 2002, Applicants respectfully request reconsideration of the above-identified application in view of the following amendment and remarks.

## **IN THE CLAIMS**

Please cancel Claims 44-60.

Please add the following claims:

02/14/2003 NMOHAMM1 00000033 09531163

01 FC:1201

168.00 OP